

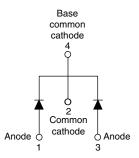


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Vishay Semiconductors

HEXFRED® Ultrafast Soft Recovery Diode, 2 x 8 A





PRODUCT SUMMARY						
Package	TO-220AB					
I _{F(AV)}	2 x 8 A					
V_{R}	600 V					
V _F at I _F	1.4 V					
t _{rr} typ.	18 ns					
T _J max.	150 °C					
Diode variation	Common cathode					

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Designed and qualified according to JEDEC®-JESD47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>





ROHS
COMPLIANT
HALOGEN
FREE
Available

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- · Higher frequency operation
- · Reduced snubbing
- · Reduced parts count

DESCRIPTION

VS-HFA16TA60C... is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A per leg continuous current, the VS-HFA16TA60C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the to portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA16TA60C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Cathode to anode voltage	V_R		600	V			
Maximum continuous forward current	I_	T _C = 100 °C	8				
per device	- I _F	1C = 100 C	16	Α			
Single pulse forward current	I _{FSM}		60	A			
Maximum repetitive forward current	I _{FRM}		24				
Maximum power dissipation	P _D	T _C = 25 °C	36	W			
waxiiiuiii power uissipatiofi		T _C = 100 °C	14] vv			
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C			



VS-HFA16TA60CPbF, VS-HFA16TA60C-N3

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ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	Ι _R = 100 μΑ		600	-	-	
Maximum forward voltage		I _F = 8 A		-	1.4	1.7	V
	V_{FM}	I _F = 16 A	See fig. 1	-	1.7	2.1	
		I _F = 8 A, T _J = 125 °C		-	1.4	1.7	
Maximum reverse		V _R = V _R rated	See fig. 2	-	0.3	5.0	
leakage current	I _{RM}	$T_J = 125$ °C, $V_R = 0.8 \times V_R$ rated	See fig. 2	-	100	500	μΑ
Junction capacitance	C _T	V _R = 200 V See fig. 3		-	10	25	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body		-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
	t _{rr}	$I_F = 1.0 \text{ A}, dI_F/dt = 200$	A/μs, V _R = 30 V	-	18	-		
Reverse recovery time See fig. 5 and 10	t _{rr1}	T _J = 25 °C		-	37	55	ns	
See lig. 5 and 10	t _{rr2}	T _J = 125 °C	$I_F = 8.0 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	55	90		
Peak recovery current	I _{RRM1}	T _J = 25 °C		-	3.5	5.0	A nC	
See fig. 6	I _{RRM2}	T _J = 125 °C		-	4.5	8.0		
Reverse recovery charge	Q _{rr1}	T _J = 25 °C		-	65	138		
See fig. 7	Q _{rr2}	T _J = 125 °C		-	124	360	IIC	
Peak rate of fall recovery current during t _b	dI _{(rec)M} /dt1	T _J = 25 °C		-	240	-	A/µs	
See fig. 8	dI _{(rec)M} /dt2	T _J = 125 °C		-	210	-	ΑνμS	

THERMAL - MECHANICAL SPECIFICATIONS PER LEG								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C		
Junction to case, single leg conducting	0		-	-	3.5			
Junction to case, both legs conducting	- R _{thJC}		-	-	1.75	K/W		
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	80	N/VV		
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-			
Weight			-	2.0	-	g		
vveignt			-	0.07	-	oz.		
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style TO-220AB		HFA16	TA60C			

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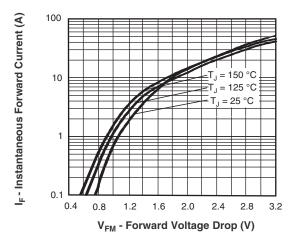


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

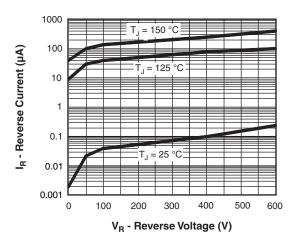


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

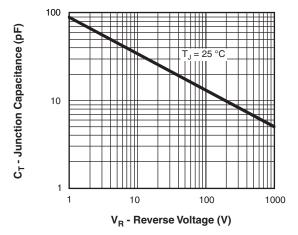


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

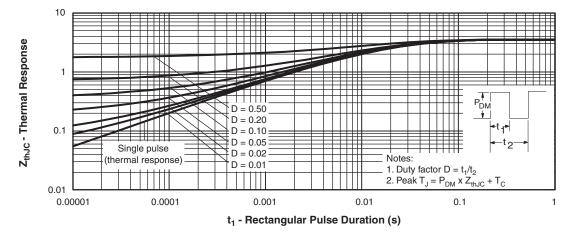


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)



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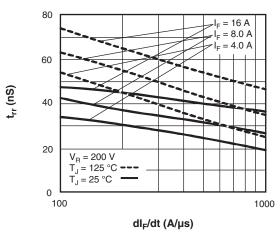


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

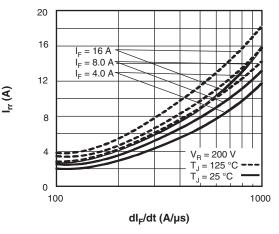


Fig. 6 - Typical Recovery Current vs. dI_F/dt (Per Leg)

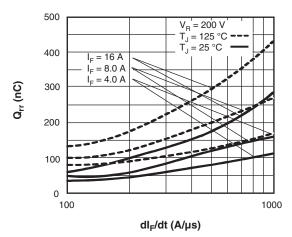


Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

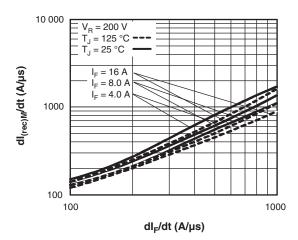
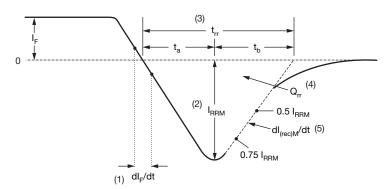


Fig. 8 - Typical dl_{(rec)M}/dt vs. dl_F/dt (Per Leg)



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_{r}$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) dI_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

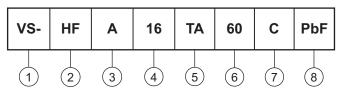
Fig. 9 - Reverse Recovery Waveform and Definitions

VS-HFA16TA60CPbF, VS-HFA16TA60C-N3

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - HEXFRED® family

3 - Electron irradiated

4 - Current rating (16 = 16 A)

- Package:

4 TA = TO-220AB

6 - Voltage rating (60 = 600 V)

7 - Circuit configuration:

C = common cathode

8 - Environmental digit:

PbF = lead (Pb)-free and RoHS-compliant

-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)								
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION					
VS-HFA16TA60CPbF	50	1000	Antistatic plastic tube					
VS-HFA16TA60C-N3	50	1000	Antistatic plastic tube					

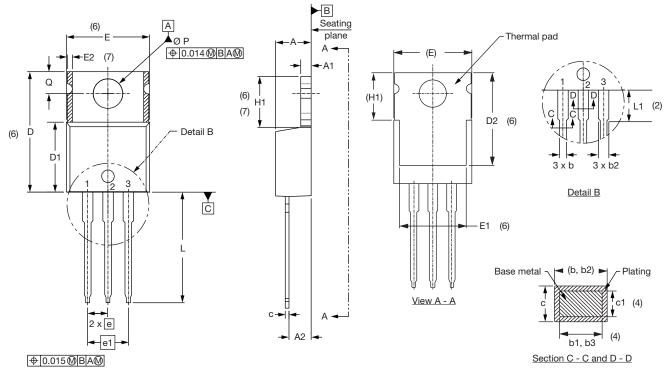
LINKS TO RELATED DOCUMENTS						
Dimensions <u>www.vishay.com/doc?95222</u>						
Part marking information	TO-220ABPbF	www.vishay.com/doc?95225				
	TO-220AB-N3	www.vishay.com/doc?95028				
SPICE model		www.vishay.com/doc?95689				



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TO-220AB

DIMENSIONS in millimeters and inches



Lead assignments



- Anode/open
 Cathode
- 3. Anode

Diodes

Conforms to JEDEC outline TO-220AB

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
С	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6

SYMBOL		MILLIN	IETERS	INC	HES	NOTES
STIVI	STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Е		10.11	10.51	0.398	0.414	3, 6
Е	1	6.86	8.89	0.270	0.350	6
E	2	-	0.76	-	0.030	7
e)	2.41	2.67	0.095	0.105	
e	1	4.88	5.28	0.192	0.208	
Н	1	6.09	6.48	0.240	0.255	6, 7
L	-	13.52	14.02	0.532	0.552	
L	1	3.32	3.82	0.131	0.150	2
Ø	Р	3.54	3.73	0.139	0.147	
C)	2.60	3.00	0.102	0.118	
ϵ)	90° to 93°		90° t	o 93°	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- $^{(7)}$ Dimensions E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, except A2 (maximum) and D2 (minimum) where dimensions are derived from the actual package outline

Lead tip



Legal Disclaimer Notice

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